



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **L-0505-05** DATE: 6/3/2005
Product Affected: IDTCSPUA877 & IDT74SSTUA32866
All package options

Date Effective: June 3, 2005

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☐ Product Mark
☐ Back Mark
☒ Date Code
☐ Other

Contact: Bimla Paul
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Attachment: ☐ Yes ☒ No

Samples: N/A

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
☐ Wafer Fabrication Process
☐ Assembly Process
☐ Equipment
☐ Material
☐ Testing
☐ Manufacturing Site
☒ Data Sheet
☐ Other

V_{DDQ} max and V_{OL} & V_{OH} V_{DDQ} max change from 2.0V to 1.9V
on IDTCSPUA877 & IDT74SSTUA32866 (all package options)
to comply with JEDEC specification.

RELIABILITY/QUALIFICATION SUMMARY:

There is no change in product quality and reliability.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____

☐ *Approval for shipments prior to effective date.*

Name/Date: _____

E-Mail Address: _____

Title: _____

Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____

DATE: _____